



The GreenMOS®


at $T_j=25^\circ\text{C}$ unless otherwise noted

Drain-source voltage	V_{DS}	600	V
Gate-source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	53	A
Continuous drain current ¹⁾ , $T_C=100^\circ\text{C}$		33.3	
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D, \text{pulse}}$	159	A
Continuous diode forward current ¹⁾ , $T_C=25^\circ\text{C}$	I_S	53	A
Diode pulsed current ²⁾ , $T_C=25^\circ\text{C}$	$I_{S, \text{pulse}}$	159	A
Power dissipation ³⁾ , $T_C=25^\circ\text{C}$	P_D	390	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	1200	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\dots 480\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\dots 480\text{ V}$, $I_{SD} = I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C

Thermal resistance, junction-case	R_{JC}	0.32	°C/W
Thermal resistance, junction-ambient ⁴⁾	R_{JA}	62	°C/W

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Drain-source breakdown voltage	BV_{DSS}	600			V	$V_{GS}=0\text{ V}, I_D=1\text{ mA}$
		650				$V_{GS}=0\text{ V}, I_D=1\text{ mA}, T_j=150^\circ\text{C}$
Gate threshold voltage	$V_{GS(\text{th})}$	2.0		4.0	V	$V_{DS}=V_{GS}, I_D=1\text{ mA}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		0.055	0.069		$V_{GS}=10\text{ V}, I_D=26.5\text{ A}$
			0.135			$V_{GS}=10\text{ V}, I_D=26.5\text{ A}, T_j=150^\circ\text{C}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=30\text{ V}$
				-100		$V_{GS}=-30\text{ V}$
Drain-source leakage current	I_{DSS}			1	μA	$V_{DS}=600\text{ V}, V_{GS}=0\text{ V}$

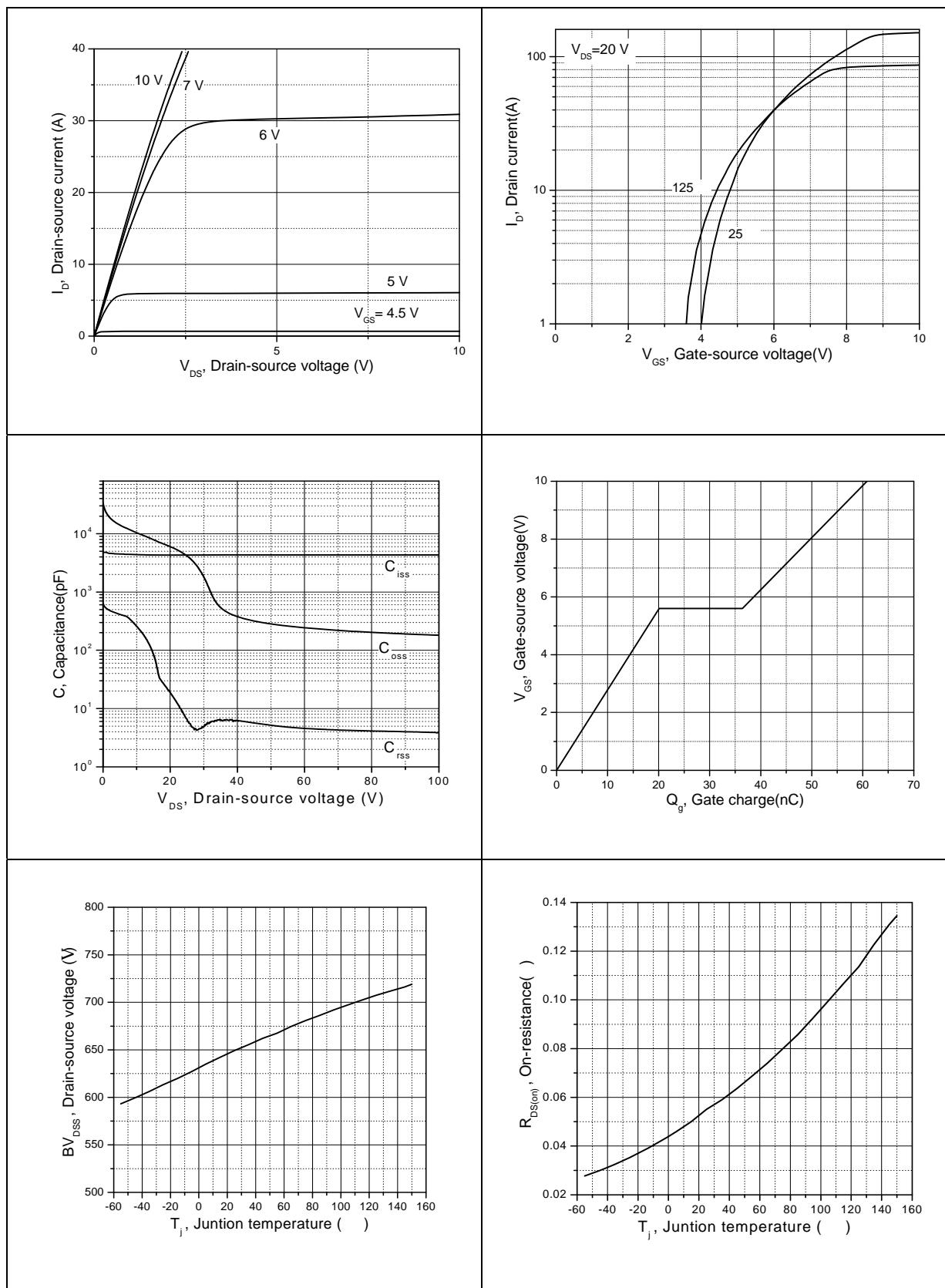


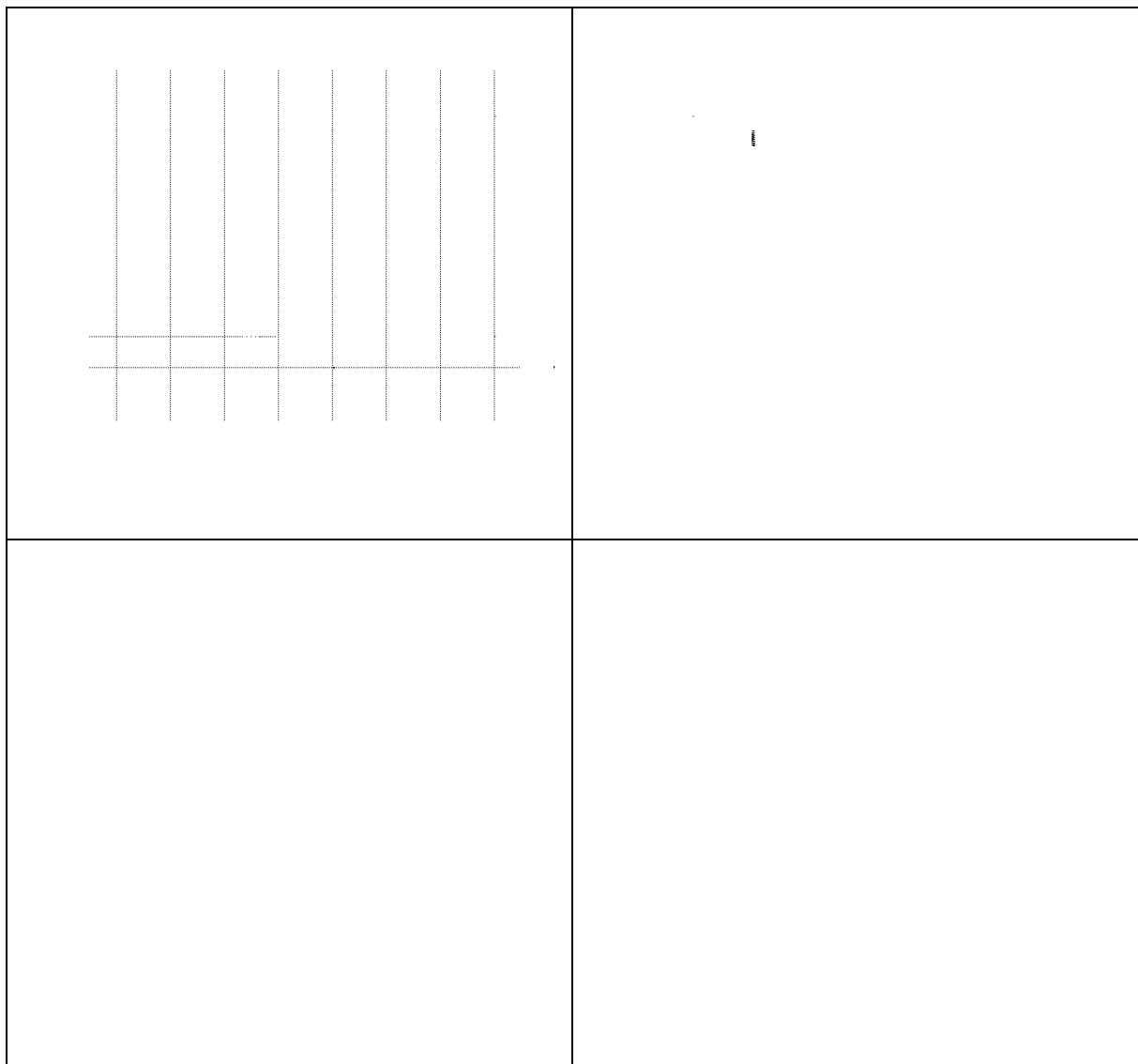
Input capacitance	C_{iss}		4321		pF	$V_{GS}=0\text{ V}$, $V_{DS}=50\text{ V}$, $f=200\text{ KHz}$
Output capacitance	C_{oss}		283.3		pF	
Reverse transfer capacitance	C_{rss}		5.2		pF	
Turn-on delay time	$t_{d(on)}$		89.7		ns	$V_{GS}=10\text{ V}$, $V_{DS}=400\text{ V}$, $R_G=25\text{ }\Omega$, $I_D=30\text{ A}$
Rise time	t_r		104.4		ns	
Turn-off delay time	$t_{d(off)}$		143.6		ns	
Fall time	t_f		73.2		ns	

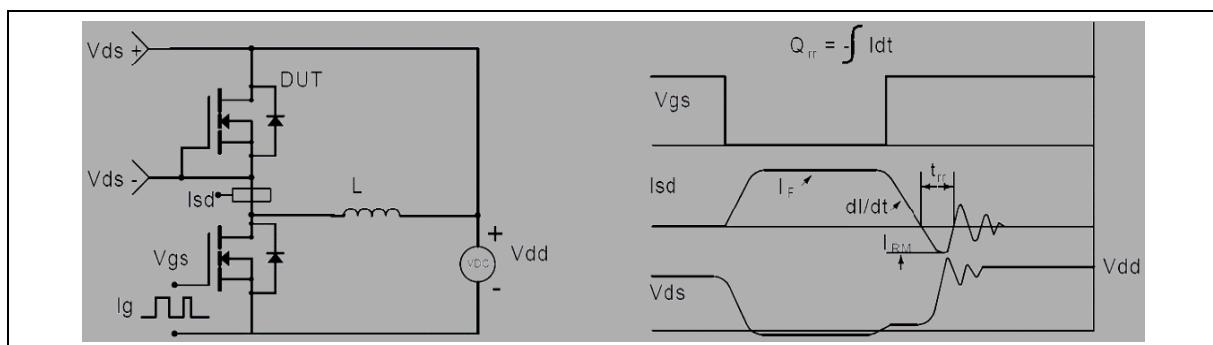
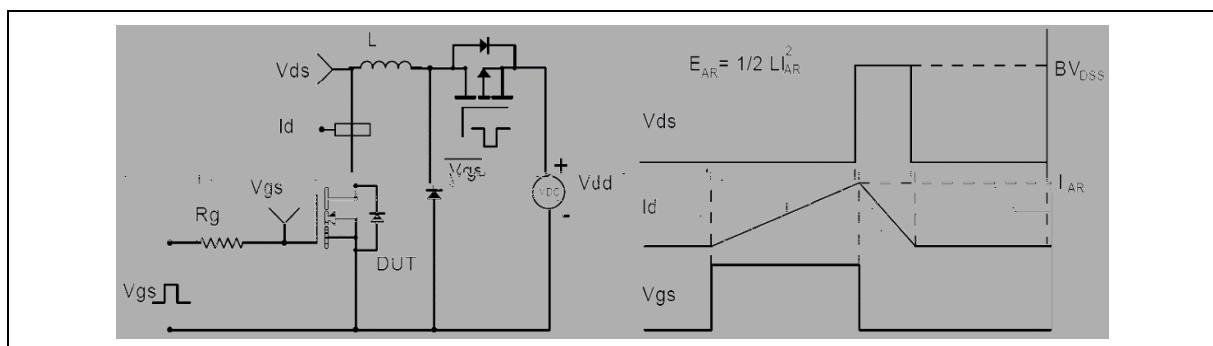
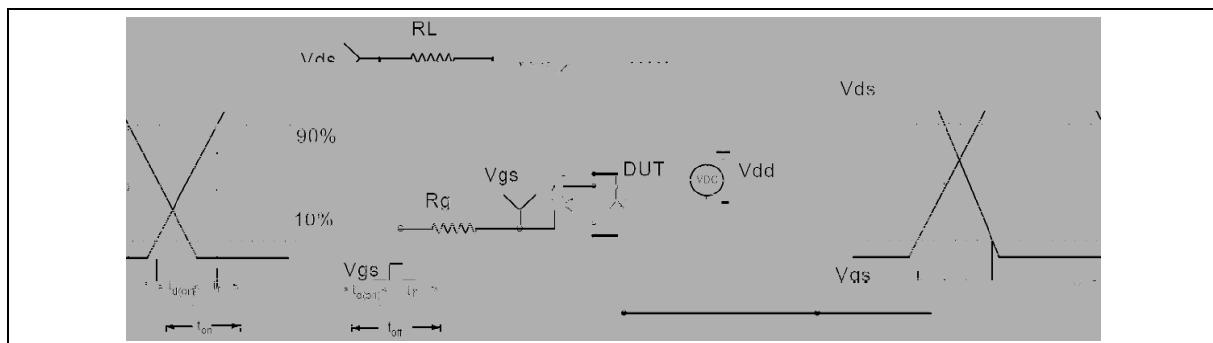
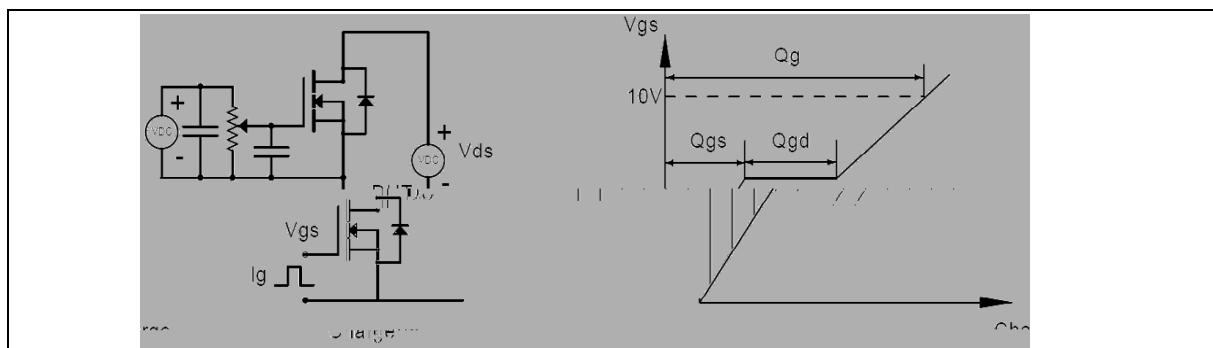
Total gate charge	Q_g		60.5		nC	$V_{GS}=10\text{ V}$, $V_{DS}=400\text{ V}$, $I_D=30\text{ A}$
Gate-source charge	Q_{gs}		20.1		nC	
Gate-drain charge	Q_{gd}		16.3		nC	
Gate plateau voltage	$V_{plateau}$		5.6		V	

Diode forward voltage	V_{SD}			1.3	V	$I_S=53\text{ A}$, $V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		532		ns	
Reverse recovery charge	Q_{rr}		10.5		μC	
Peak reverse recovery current	I_{rrm}		36.1		A	

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{JA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^\circ\text{C}$.
- 5) $V_{DD}=100\text{ V}$, $V_{GS}=10\text{ V}$, $L=80\text{ mH}$, starting $T_j=25\text{ }^\circ\text{C}$.









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